## **VGAP-CG1-AS-A1 Specification**

### 1. Features and Application

- (1) This product is manufactured in ISO/TS16949 certified production factory.
- (2) This product is qualified according to AEC-Q200.
- (3) This product is for GPS L1 band, 1575.42 MHz, Glonass...

### 2. Explanation of Part Number

VGAP - 
$$\frac{C}{(1)} \frac{G1}{(2)} - \frac{A}{(3)} \frac{S}{(4)} - \frac{A1}{(5)}$$

(1) Product Type: Chip Antenna

(2) Center Frequency/Band Code: M4 - Dual-band(GPS + Glonass)

(3) Size Code: 5.0\*3.6 mm (Length\*Width)

(4) Special Code: RoHS Compliant(5) Design Revision Code: Rev.1

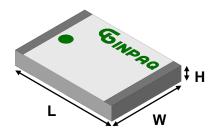
### 3. Electrical Specification

Item	Specification		
Frequency Band	1570 ~ 1580 MHz	1593 ~ 1610 MHz	
Polarization	Linear		
Impedance	50 ohm Typ.		
VSWR	Less than 2.0	Less than 2.0	
*Peak Gain	3.62 dBi Typ.	3.71 dBi Typ.	
*Peak Efficiency	75.7% Typ.	77.2 % Typ.	

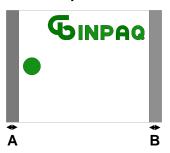
\* Test condition: Test board size 80\*40 mm Matching circuit may be required

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TITLE: VGAP-CG1-AS-A1 Specification		DOCUMENT	ENS000063510	SPEC REV.
		NO.	LN3000003310	A2

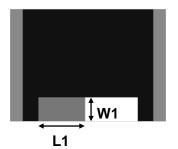
# 4. Physical Dimension







**Bottom view** 



Marking is Green

L	5.20 ± 0.30
w	$3.70 \pm 0.30$
н	$0.70 \pm 0.15$
A	$0.45 \pm 0.25$
В	$0.45 \pm 0.25$
L1	1.10 ± 0.20
W1	$0.55 \pm 0.20$

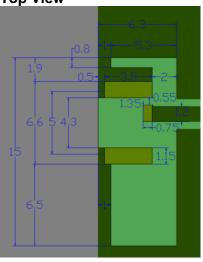
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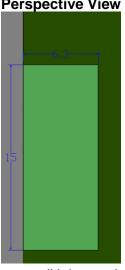
## 5. Recommend PCB Layout

Layout Ground. Matching Circuit Feed line Pad Clearance Area (15 x 6.3 mm)<sub>e</sub> ed for tuning frequency, 🕡 and can be eliminated in real application.

### **Pad Dimensions on PCB Layout Top View**



### **Perspective View**

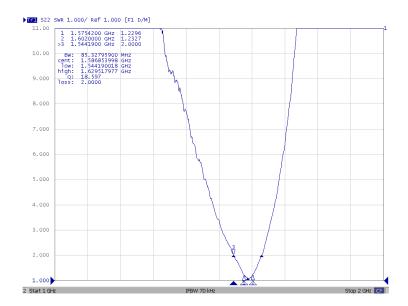


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### 6. Electrical Characteristics

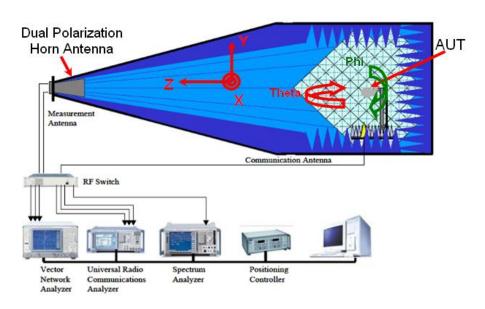
#### **VSWR**



Mark	Frequency	VSWR
1	1575 MHz	1.3
2	1602 MHz	1.3

#### **Radiation Pattern**

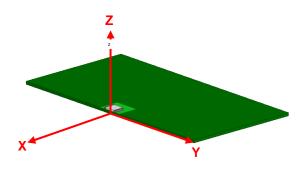
The Gain pattern is measured in INPAQ's FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

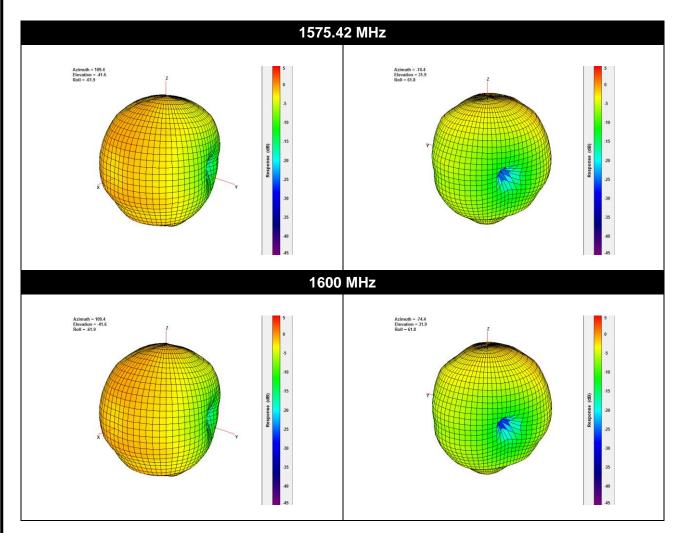


3D Chamber Definition

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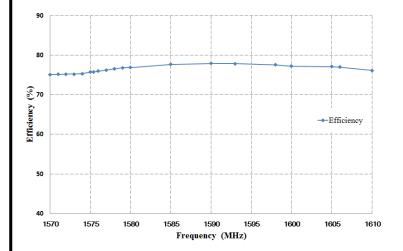
### 3D Gain Pattern





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## **Efficiency**

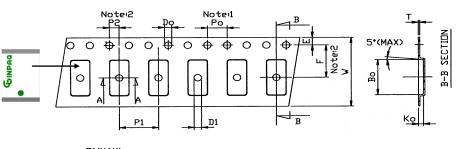


Frequency (MHz)	Efficiency (%)
1570	75.1
1575.42	75.7
1580	76.8
1590	77.9
1600	77.2
1610	76.1

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## 7. Taping Package and Label Marking

- (1) Quantity/Reel: 2000pcs/Reel
- (2) Carrier tape dimensions



(Unit: mm)

	( •
Symbol	Spec.
Ро	4. 00±0. 1
P1	8. 00±0. 1
P2	2.00±0.05
Do	1.55±0.05
D1	1.50(MIN)
E	1.75±0.1
F	5.50±0.05
10Po	40.00±0.2
W	12.00±0.1
T	0. 25±0. 05



 $A0 = 4.10 \pm 0.10 \text{ mm}$ 

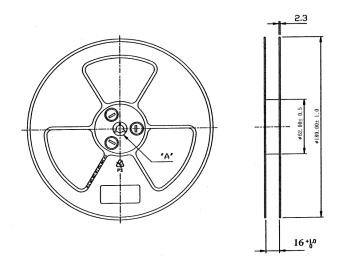
 $B0 = 5.60 \pm 0.10 \text{ mm}$ 

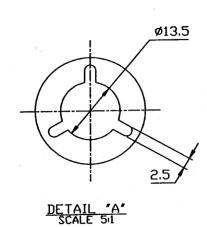
 $K0 = 1.02 \pm 0.10 \text{ mm}$ 

#### Notice:

- 1. 10 Sprocket hole pitch cumulative tolerance is ±0.1mm
- Pocket position relative to sprocket hole measured as true position of pocket not pocket hole.
   Ao & Bo measured on a place 0.3mm above the bottom of the pocket to top surface of the carrier.
- Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- 5. Carrier camber shall be not than 1mm per 100mm through a length of 250mm.

### (3) Taping reel dimensions





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### 8. Environmental Characteristics

This product is qualified according to AEC-Q200.

### (1) Reliability Test

Item	Condition	Specification
High Temperature Storage	150°C → 1000hours	No Damaged
Temperature Cycling	-55°C 30min/125°C 30min ⋅ 1000 cycle	No Damaged
Biased Humidity	85°C 、85% RH,1000hours	No Damaged
Resistance to Solvent	Add Aqueous wash chemical OKEMCLEAN for 5 min	No Damaged
Mechanical Shock	1500G 0.5 ms , X,Y,Z axis 3 time	No Damaged
Vibration	<ol> <li>Frequency: 10 to 2000 Hz</li> <li>5g's for 20 min</li> <li>Duration time: 2hr for each in X,Y,Z</li> </ol>	No Damaged
Resistance to Soldering Heat	Brush flux and put the board into solder bath 260 $^\circ\!$	No Damaged
Solderability Test	1. 8 hours ± 15 min. steam conditioning 2. Put the sample on board by tape. 3. Brush flux and put the board into solder bath 260±5℃ , 5±1 sec	
Board Flex	2mm for 60sec.	No Damaged
Termination strength (SMD)	1.8Kgf <sup>,</sup> 60sec	No Damaged

### (2) Storage condition

#### (a) At warehouse:

The temperature should be within  $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

#### (b) On board:

The temperature should be within -40  $\sim$  85°C and humidity should be less than 85% RH.

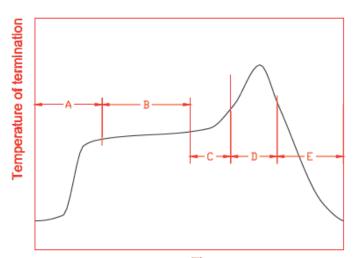
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## (3) Operating temperature range

Operating temperature range : -40 ~ +105°C.

### 9. Recommended reflow soldering

Reference: J-STD-020C



1 <sup>st</sup> rising temperature	The normal to Preheating temperature	30s to 60s
Preheating	140°C to 160°C	60s to 120s
2 <sup>nd</sup> rising temperature	Preheating to 200°C	20s to 40s
D Main heating	if 220℃	50s∼60s
	if 230℃	40s∼50s
	if 240℃	30s∼40s
	if 250℃	20s~40s
	if 260°C	20s~40s
Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s
	Preheating  2 <sup>nd</sup> rising temperature  Main heating	The string temperature  Preheating  2nd rising temperature  Preheating to 200°C  if 220°C  if 230°C  if 240°C  if 250°C  if 260°C

### (1) Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

### (2) Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

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